

Claims

Please replace all preceding sets of claims with the attached amended claims:

1. (Currently Amended) A method for production of moldings for switching devices for low-voltage, medium-voltage and high-voltage comprising, characterized in that providing a plurality of switching chambers with a cast surround composed of a first encapsulation compound, then encapsulating the plurality of switching chambers together with connections into a block composed of at least one second encapsulation compound thus creating a direct encapsulation of components and wherein a mixture of balls with a predetermined distribution of diameters of size Dx is introduced into said first or said second the encapsulation compound thus creating direct encapsulation of components.

2. (Currently Amended) The method of claim 1, wherein A method for production of moldings for switching devices for low-voltage, medium-voltage and high-voltage, in particular as claimed in claim 1, characterized in that a said mixture of hollow balls are hollow with a predetermined distribution of external diameters of size Dx is introduced into the encapsulation compound.

3. (Cancelled)

4. (Currently Amended) The method of claim 1, ~~2 or 3,~~ characterized in that wherein epoxy resin is used as the first encapsulation compound, and silicone, polyurethane or a polyurethane derivative is used as the second encapsulation compound.

5. (Cancelled)

6. (Currently Amended) The method of claim 1 wherein as claimed in one of the preceding claims, characterized in that the balls ~~or the hollow balls~~ are composed of glass.

7. (Currently Amended) The method of claim 1 wherein as claimed in claim 1, ~~2 or 3,~~ characterized in that the balls ~~or the hollow balls~~ are composed of

ceramic, preferably of aluminum nitride.

8. (Currently Amended) The method of claim 1 wherein as claimed in one of the preceding claims, characterized in that the filling level of said balls is set to be between 50 and 90%.

9. (Currently Amended) The method of claim 1 wherein as claimed in one of the preceding claims, characterized in that other fillers in the form of small particles are mixed with the balls and/or hollow ball mixture.

10. (Currently Amended) The method of claim 1 wherein as claimed in one of the preceding claims, characterized in that the other fillers include ~~are~~ quartz powder or synthetic silica flour.

11. (Currently Amended) The method of claim 1 wherein as claimed in one of the preceding claims, characterized in that the external diameters of the balls or hollow balls or particles have a bandwidth of 0.01 mm to 10 mm.

12. (Currently Amended) The method of claim 1 wherein as claimed in one of the preceding claims, characterized in that the balls, hollow balls or particles have a mean density of 0.2 g/cm^3 .

13. (Currently Amended) The method of claim 1 wherein as claimed in one of the preceding claims, characterized in that the balls, hollow balls or particles have a mean density of 0.37 g/cm^3 .

14. (Currently Amended) The method of claim 2 wherein as claimed in one of the preceding claims, characterized in that the hollow balls have a diameter of up to 200 micrometers.

15. (Currently Amended) The method of claim 2 wherein as claimed in one of the preceding claims, characterized in that the hollow balls have an effective density between 0.1 and 0.6 g/cm^3 .

16. (Currently Amended) The method of claim 1 wherein as claimed in one of

~~the preceding claims, characterized in that the solid balls have a density between 2.0 and 7.0 g/cm³.~~

Claims 17 - 25 (Cancelled) A switching device for low-voltage, medium-voltage and high-voltage, having encapsulated moldings, characterized in that a mixture of balls and/or hollow balls and/or particles with a predetermined distribution of diameters of size Dx is introduced into the first encapsulation compound thus creating direct encapsulation of moldings, and the moldings of a switching device are composed of electrically insulating materials.

18. (Withdrawn) A switching device for low-voltage, medium-voltage and high-voltage, having encapsulated moldings, characterized in that the second encapsulation compound in which the moldings with cast surrounds are inserted and/or are once again encapsulated in this way is composed of electrically insulating materials, such as silicone, epoxy resin or polyurethane.

19. (Withdrawn) The switching device as claimed in claim 17 or 18, characterized in that at least one switching chamber is provided with a cast surround composed of a first encapsulation compound, and is then encapsulated together with connections into a block composed of at least one second encapsulation compound such as silicone, soft epoxy or plastics.

20. (Withdrawn) The switching device as claimed in one of claims 17 to 19, characterized in that epoxy resin is used as the first encapsulation compound, and silicone, polyurethane or a polyurethane derivative is used as the second encapsulation compound.

21. (Withdrawn) The switching device as claimed in claim 20, characterized

in that said particles or balls are introduced into the first and/or into the second encapsulation compound.

22. (Withdrawn) The switching device as claimed in claim 21, characterized in that the balls or hollow balls are composed of glass or ceramic.

23. (Withdrawn) The switching device as claimed in one of claims 17 to 22, characterized in that the balls or hollow balls are composed of aluminum-nitride ceramic.

24. (Withdrawn) The switching device as claimed in one of the preceding claims 17 to 22, characterized in that the moldings or components of a switching device for each phase of a three-phase supply are each encapsulated to form a sealed block.

25. (Withdrawn) The switching device as claimed in claim 24, characterized in that the respective block is provided with heat-dissipating connection elements (2).